

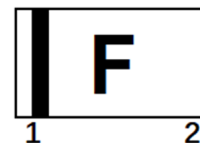
Features

- * Low forward voltage drop
- * Low reverse current
- * RoHS Compliant
- * REACH & SVHC Compliant
- * Halogen Compliant
- * CSP0603-2L Package

Package and Marking Diagram



CSP0603-2L



Top view

Circuit Diagram



Ordering Information

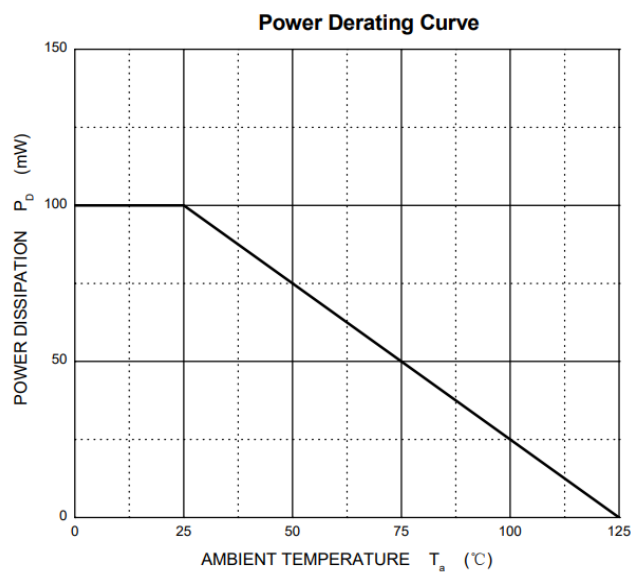
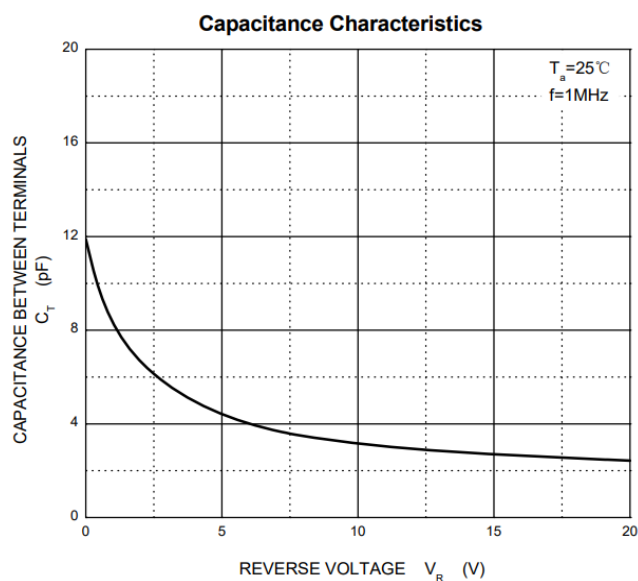
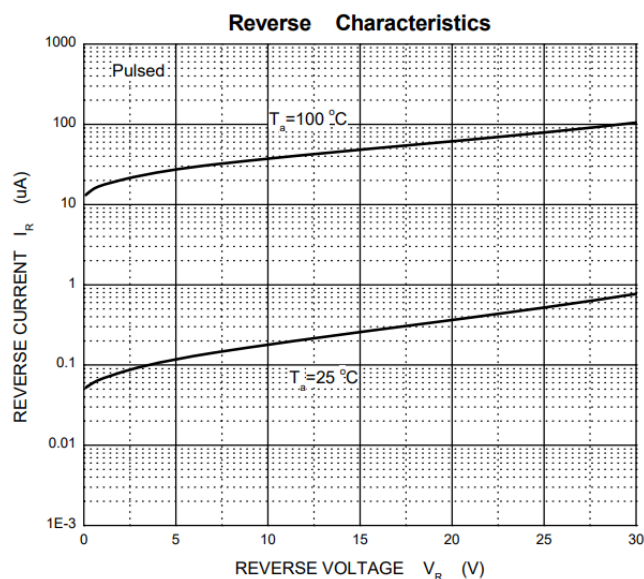
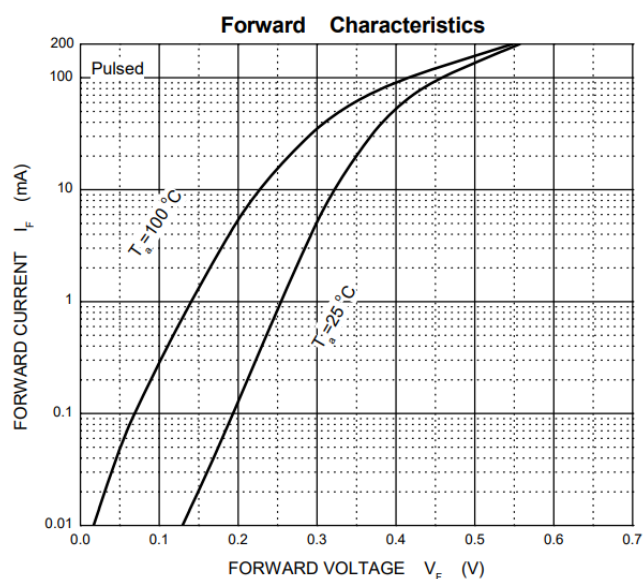
Part Number	Packaging	Reel Size
DSF01S30SL,L3F-CN	10000/Tape & Reel	7 inch

Absolute Maximum Ratings ($T_A=25^{\circ}\text{C}$ unless otherwise specified)

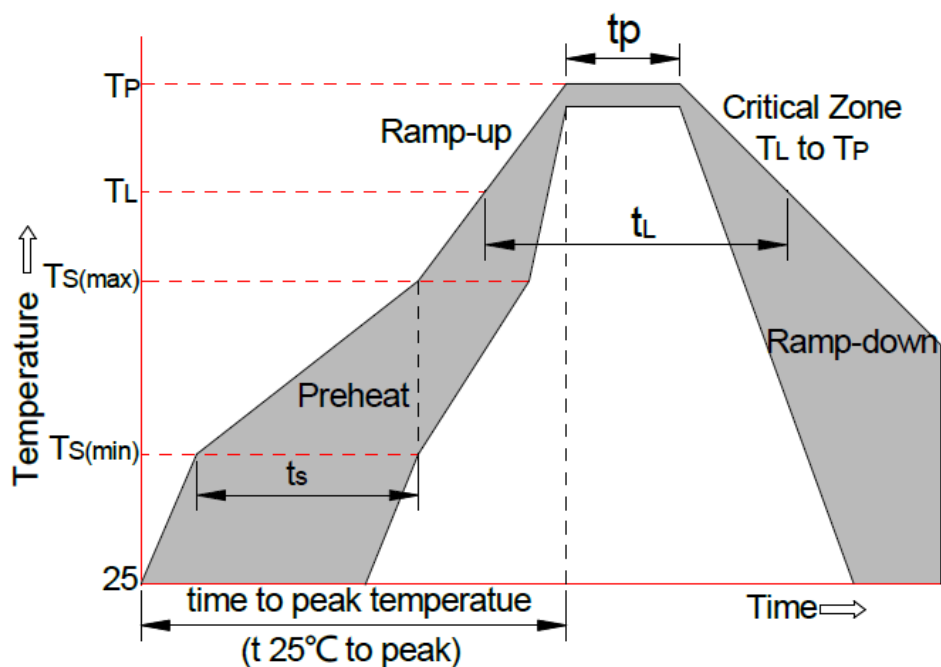
Parameter	Symbol	Value	Unit
Repetitive peak reverse voltage	V_{RRM}	30	V
DC blocking voltage	V_R	30	V
Continuous forward current	I_O	100	mA
Non-repetitive peak forward current @ $t=8.3\text{ms}$	I_{FSM}	500	mA
Power dissipation	P_D	100	mW
Junction temperature	T_J	-40 to $+125$	$^{\circ}\text{C}$
Storage temperature	T_{STG}	-55 to $+150$	$^{\circ}\text{C}$

Electrical Characteristics ($T_A=25^{\circ}\text{C}$ unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Breakdown voltage	V_{BR}	$I_T = 50\mu\text{A}$	30			V
Reverse leakage current	I_R	$V_R = 10\text{V}$		0.2	2	μA
Reverse leakage current	I_R	$V_R = 30\text{V}$			3	μA
Forward voltage	V_F	$I_F = 10\text{mA}$			440	mV
Forward voltage	V_F	$I_F = 100\text{mA}$			580	mV

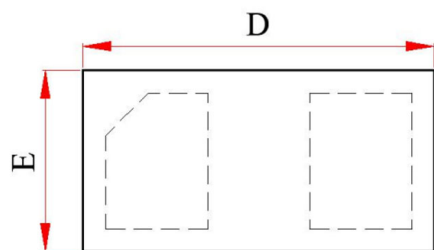
Typical Performance Characteristics ($T_A=25^{\circ}\text{C}$ unless otherwise Specified)


Soldering Parameters

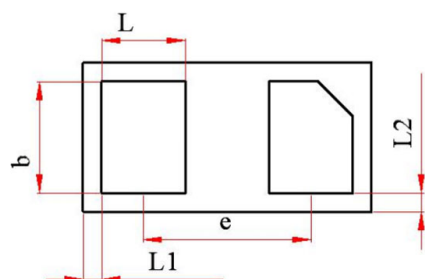


Reflow Conditions		Pb-Free Assembly
Pre-heat	-Temperature Min (T_S (min))	+150°C
	-Temperature Max (T_S (max))	+200°C
	-Time (Min to Max) (t_s)	60-180 secs
Average ramp up rate(Liquid us Temp (T_L) to peak)		3°C/sec. Max
$T_{S(max)}$ to T_L -Ramp-up Rate		3°C/sec. Max
Reflow	-Temperature (T_L) (Liquid us)	+217°C
	-Temperature (t_L)	60-150 secs
Peak Temp (T_P)		+260(+0/-5)°C
Time within 5°C of actual Peak Temp (t_p)		30 secs. Max
Ramp-down Rate		6 °C/secs. Max
Time 25°C to Peak Temp (T_P)		8 min. Max
Do not exceed		+260°C

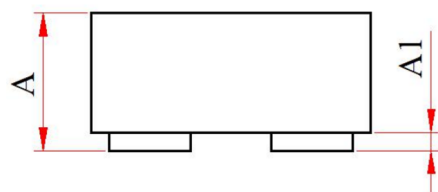
CSP0603-2L Package Outline Drawing



TOP VIEW



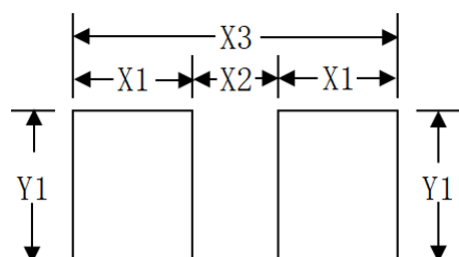
BOTTOM VIEW



SIDE VIEW

SYM	DIMENSIONS					
	MILLIMETERS			INCHES		
	Min	Typ	Max	Min	Typ	Max
A	0.280	--	0.340	0.0110	--	0.0134
A1	--	--	0.050	--	--	0.0020
D	0.590	0.620	0.640	0.0232	0.0244	0.0252
E	0.290	0.320	0.340	0.0114	0.0126	0.0134
b	0.215	0.240	0.265	0.0085	0.0094	0.0104
L	0.155	0.180	0.205	0.0061	0.0071	0.0081
L1	0.04 REF			0.0016 REF		
L2	0.04 REF			0.0016 REF		
e	0.36 BSC			0.0142 BSC		

Suggested Land Pattern



SYM	DIMENSIONS	
	MILLIMETER	INCHES
X1	0.25	0.010
X2	0.15	0.006
X3	0.65	0.026
Y1	0.30	0.012

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